Final Product Change Notification

201803040F01

Issue Date: 17-May-2018
Effective Date: 15-Aug-2018

Management Summary

NXP Semiconductors announces the qualification of epoxy CRM-1076WA/A-B for LQFP package and epoxy CRM-1033BF for SOIC20 package in TFME

Change Category

☐ Wafer Fab Process
☐ Wafer Fab Materials
☐ Wafer Fab Location
☐ Firmware

☐ Assembly Process
☑ Assembly Materials
☐ Assembly Location
☐ Other

☐ Product Marking
☐ Mechanical Specification
☐ Packing/Shipping/Labeling

☐ Test Location
☐ Test Process
☐ Test Equipment

☐ Design
☐ Errata
☐ Electrical spec./Test coverage

New Die Attach Qualification for LQFP/SOIC20W Package in TongFu Microelectronics Co. LTD

Description of Change

NXP Semiconductors announces the qualification of epoxy CRM-1076WA/A-B for LQFP package and epoxy CRM-1033BF for SOIC20 package in TongFu Microelectronics Co. LTD, Nantong, China (TFME) Facility.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-PA-07

Reason for Change

The new die attach qualification for LQFP/SOIC20W is required for supply assurance.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 15-Aug-2018

Anticipated Impact on Form, Fit, Function, Reliability or Quality

There is no change to product form, fit, function, or reliability

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: view online
Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 16-Jun-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

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